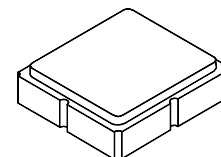


SF2159E

974 MHz
SAW Filter



SM3030-8

- **SAW Filter for Digital Television**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Moisture Sensitivity Level: 1**

Characteristics :

Balance-to-balanced Operation

Terminating Source/Load Impedance : $Z_S = 150 \Omega$

Maximum Rating

Rating	Value	Units
Input Power Level	0	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-40 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Maximum Soldering Profile, 5 cycles/ 10 seconds maximum	265	°C

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C			974		MHz
Maximum Insertion Loss, 954 to 994 MHz	IL_{MAX}			3.1	4.5	dB
1.5 dB Passband				50		MHz
Amplitude Ripple, 954 to 994 MHz				1.0	2.5	dB _{P-P}
Attenuation, Referenced to IL_{MAX}						
50 to 891.94 MHz			45	51		dB
1056.06 to 1100 MHz			44	55		
2000 to 6000 MHz			15	20		
Group Delay Ripple, 954 to 994 MHz				23	35	ns _{P-P}

Case Style	SM3030-8 3.0 x 3.0 mm Nominal Footprint
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	825, <u>YWWS</u>

Electrical Connections

	Connection	Terminals
Port 1	Balanced Input	1,2
Port 2	Balanced Output	5,6
	Ground	All Others

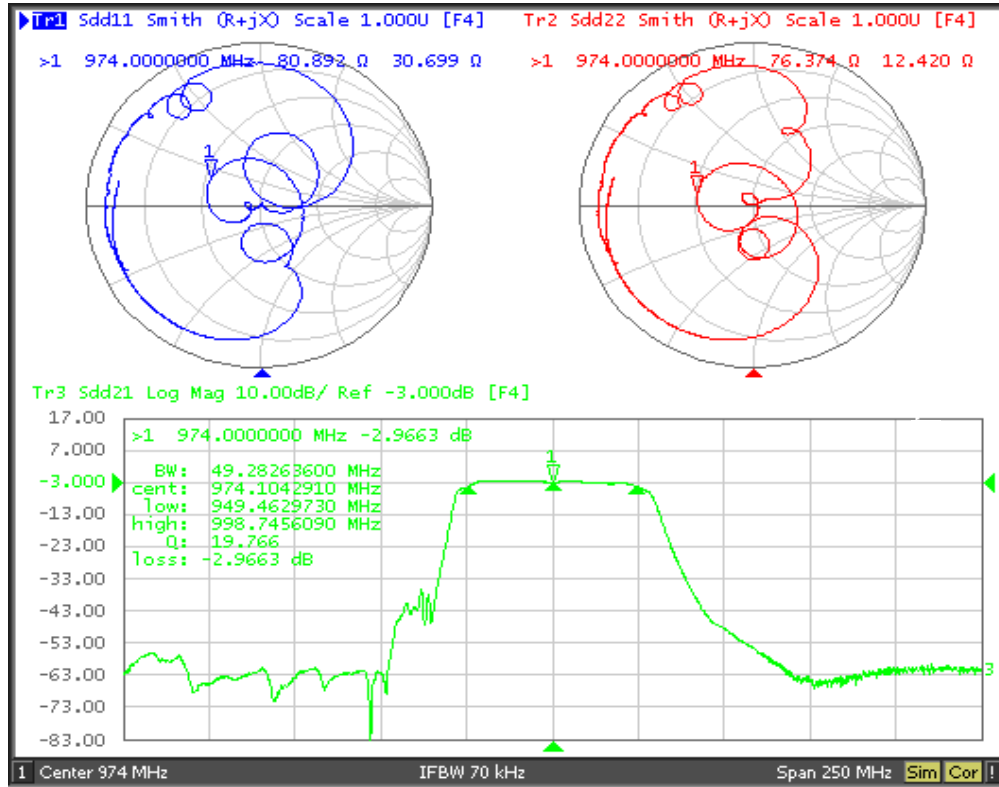
Dot Indicates Pin 1

 **CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

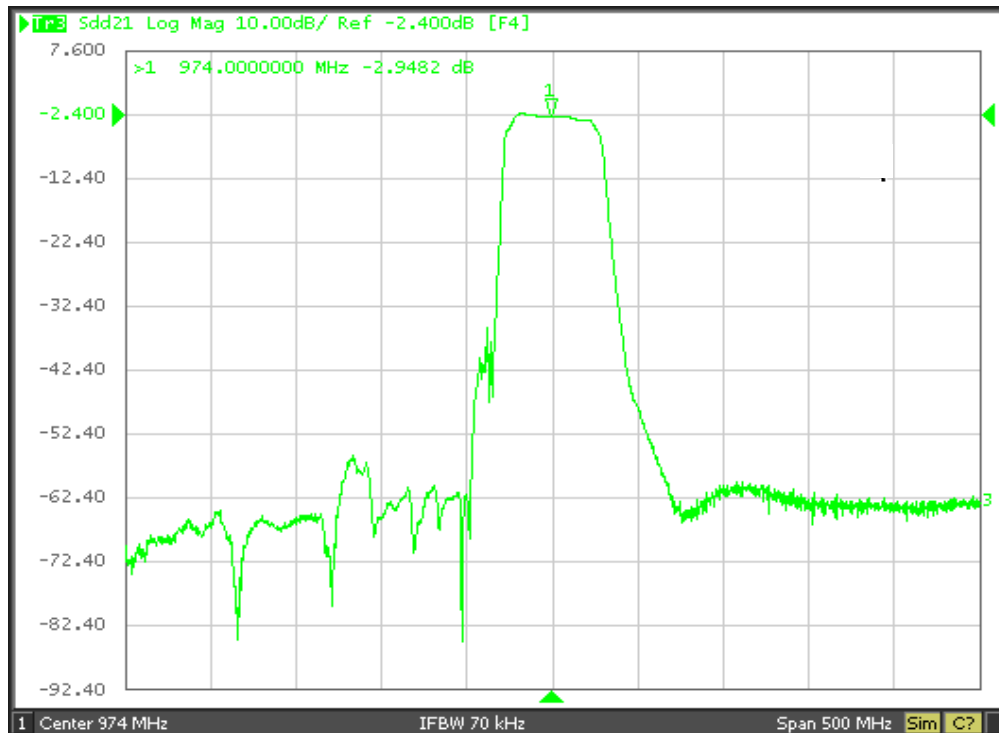
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

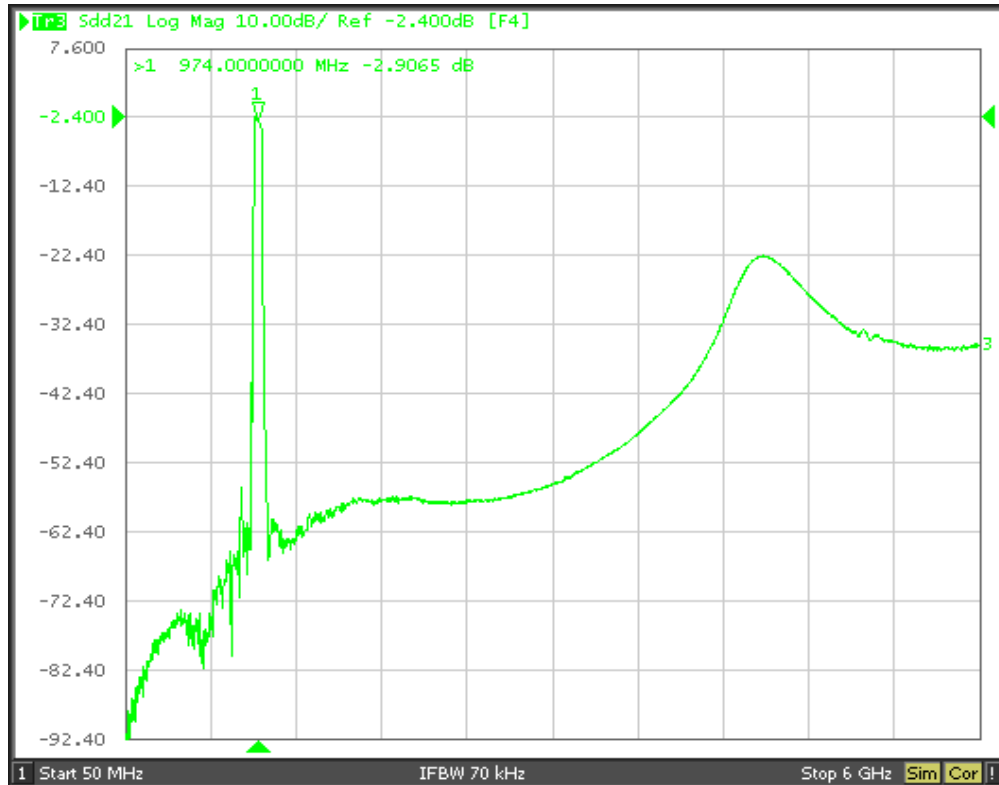
Filter S_{11} , S_{22} and S_{21} Plots



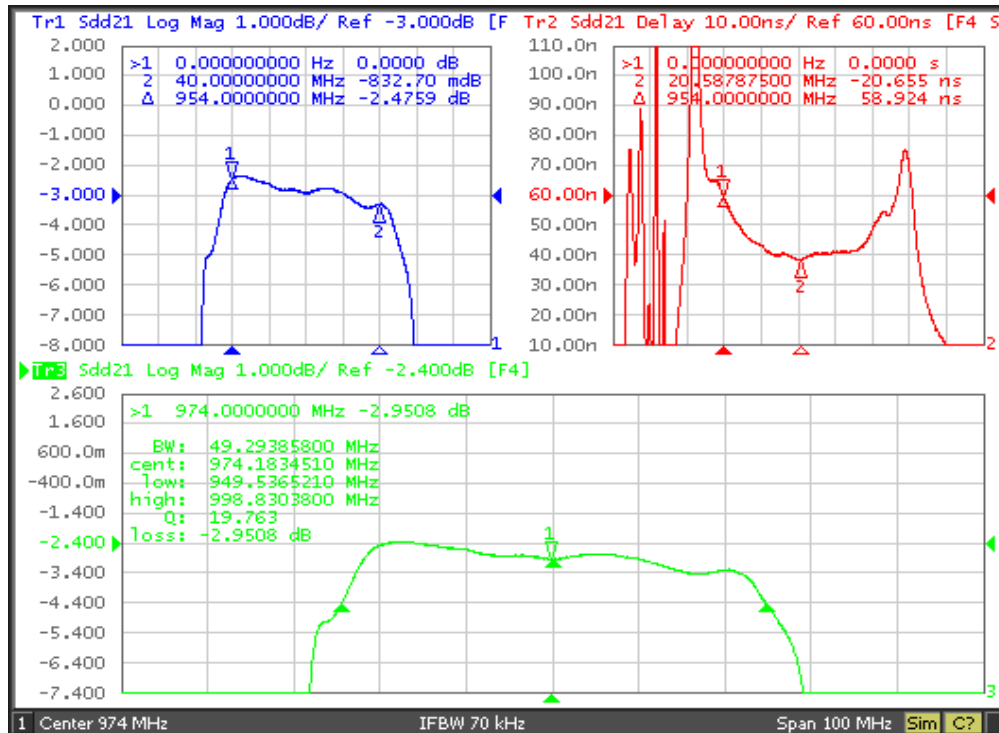
Filter Near-in Rejection



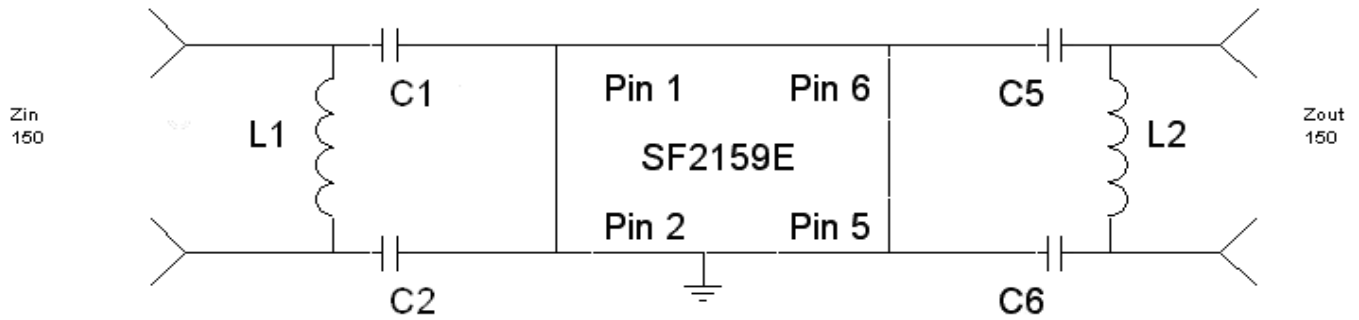
Filter Broadband Rejection



Filter Passband Amplitude and Group Delay Detail



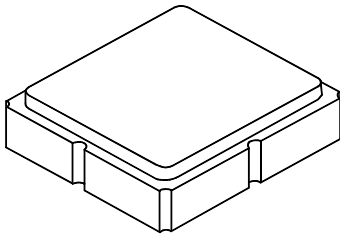
Tuning Network, 150 ohm Balanced Source/Load



All other pins grounded

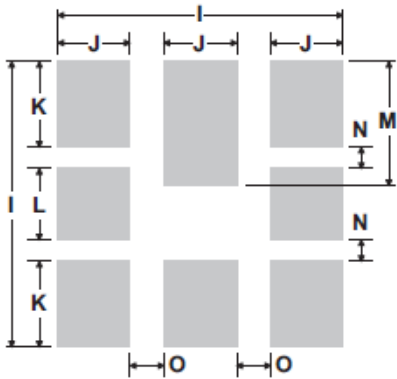
L1, L2 24 nH
C1, C2, C3, C4 22 pF

8-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.0	3.13	0.113	0.118	0.123
B	2.87	3.0	3.13	0.113	0.118	0.123
C	1.14	1.27	1.40	0.045	0.050	0.055
D	0.79	0.92	1.05	0.031	0.036	0.041
E	0.62	0.75	0.88	0.024	0.029	0.034
F	0.47	0.60	0.73	0.018	0.024	0.029
G	0.47	0.60	0.73	0.018	0.024	0.029
H	1.07	1.20	1.33	0.042	0.047	0.052
I		3.19			0.126	
J		0.81			0.032	
K		0.96			0.038	
L		0.81			0.032	
M		1.39			0.055	
N		0.23			0.009	
O		0.38			0.015	

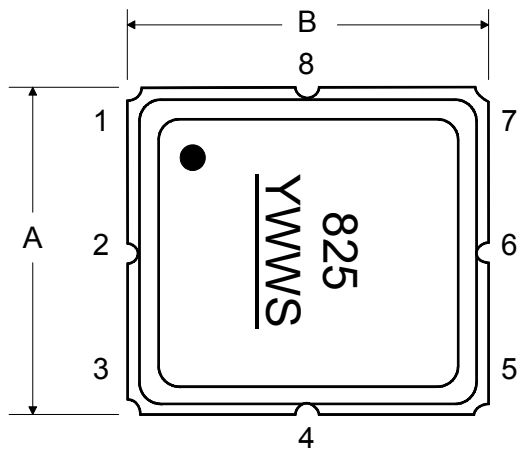


PCB Footprint Top View

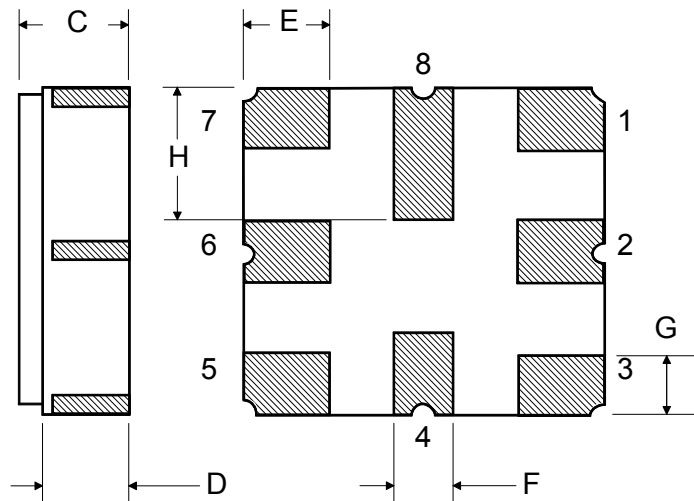
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic

TOP VIEW



BOTTOM VIEW



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

